General Purpose Low Resistance Thick Film Chip Resistors





FEATURE

- High reliability.
- Low resistance value down to $10m\Omega$.
- RoHS and Halogen-free compliance
- Compatible with reflow and wave soldering type.
- MSL class: MSL 1
- Applications:
 - Home appliances
 - Computer, notebook, workstation, tablet, and peripherals
 - Instruments and meters
 - etc.

MANUFACTURER PART NO.

For example: GR1206J0R01T5G00-GR1206 5% 10mΩ T/R-5000

Series	Size	Tol.	Nominal Resistance Value	PKG	SPQ	Feature	TCR
2 codes	4 codes	1 code	2~5 codes	1 code	1 code	1 code	2 codes
GR	1206	J	0R01	Т	5	G	00
General Purpose Low Resistance Thick Film Chip Resistors	0402 0603 0805 1206 1210 1812 2010 2512	F=1% J=5%	0R01 ³ =0.01Ω, 10mΩ 0R47=0.47Ω, 470mΩ	T=T/R [®]	4=4K 5=5K A=10K	G=Std. S=P.C. [®]	00=Refer to table as below.

Note: 1 R=Radix, 10^0 , Ω

② T/R=Taping in Reel package type

③ P.C.: Personal and Customized.

CHARACTERISTICS

Rated Power	MRC [®]	MOC ²	DWV ³	Tolerance	Value Range
1/16W	0.79A	1.98A	100V	±1%/±5%	100mΩ≦ R < 1000mΩ
1/10W	3.16A	7.90A	300V	±1%/±5%	10mΩ≦ R< 1000mΩ
1/8W	1.10A	2.79A	500V	±1%/±5%	100mΩ≦ R < 1000mΩ
1/4W	5.00A	12.50A	500V	±1%/±5%	10mΩ≦ R < 100mΩ
1/4W	1.58A	3.95A	500V	±1%/±5%	100mΩ≦ R < 1000mΩ
1/3W	5.77A	14.43A	500V	±1%/±5%	10mΩ≦ R < 100mΩ
1/2W	7.07A	17.67A	500V	±1%/±5%	10mΩ≦ R < 1000mΩ
3/4W	8.66A	21.65A	500V	±1%/±5%	10mΩ≦ R < 1000mΩ
3/4W	8.66A	21.65A	500V	±1%/±5%	10mΩ≦ R < 1000mΩ
1W	10.00A	25.00A	500V	±1%/±5%	10mΩ≦ R < 1000mΩ
	1/16W 1/10W 1/8W 1/4W 1/4W 1/3W 1/2W 3/4W	1/16W 0.79A 1/10W 3.16A 1/8W 1.10A 1/4W 5.00A 1/4W 1.58A 1/3W 5.77A 1/2W 7.07A 3/4W 8.66A 3/4W 8.66A	1/16W 0.79A 1.98A 1/10W 3.16A 7.90A 1/8W 1.10A 2.79A 1/4W 5.00A 12.50A 1/4W 1.58A 3.95A 1/3W 5.77A 14.43A 1/2W 7.07A 17.67A 3/4W 8.66A 21.65A 3/4W 8.66A 21.65A	1/16W 0.79A 1.98A 100V 1/10W 3.16A 7.90A 300V 1/8W 1.10A 2.79A 500V 1/4W 5.00A 12.50A 500V 1/4W 1.58A 3.95A 500V 1/3W 5.77A 14.43A 500V 1/2W 7.07A 17.67A 500V 3/4W 8.66A 21.65A 500V 3/4W 8.66A 21.65A 500V	1/16W 0.79A 1.98A 100V ±1%/±5% 1/10W 3.16A 7.90A 300V ±1%/±5% 1/8W 1.10A 2.79A 500V ±1%/±5% 1/4W 5.00A 12.50A 500V ±1%/±5% 1/4W 1.58A 3.95A 500V ±1%/±5% 1/3W 5.77A 14.43A 500V ±1%/±5% 1/2W 7.07A 17.67A 500V ±1%/±5% 3/4W 8.66A 21.65A 500V ±1%/±5% 3/4W 8.66A 21.65A 500V ±1%/±5%

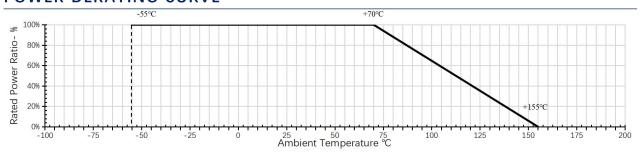
Note:

①MRC=Max. Rated Current.

② MOC=Max. Overload Current.

③ DWV=Dielectric Withstanding Voltage.

POWER DERATING CURVE



Note: Operating temperature range is from -55°C to +155°C

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RATED VOLTAGE

The resistor shall have a Rated Current which would be DC or AC corresponding to the Rated Power, and it can be calculated by formula as below.

The Rated Current of certain resistance value should be the calculated result or Max. Working Current of product series whichever less.

Formula:

I=Rated current (A) $I = \sqrt{P/R}$ P=Rated power (W) R=Nominal resistance (Ω)

DIMENSIONS

Unit: mm

Figure	Series	L	W	Н	А	В
4 -A-►	0402	1.00±0.10	0.50±0.05	0.35±0.05	0.20±0.10	0.25±0.10
H Y	0603	1.60±0.10	0.80±0.10	0.45±0.10	0.30±0.20	0.30±0.20
-48 ►	0805	2.00±0.15	1.25±0.15	0.55±0.10	0.40±0.20	0.40±0.20
L	1206	3.10±0.15	1.55±0.15	0.55±0.10	0.45±0.20	0.45±0.20
1	1210	3.10±0.10	2.60±0.20	0.55±0.10	0.50±0.25	0.50±0.20
w	1812	4.50±0.20	3.20±0.20	0.55±0.10	0.50±0.20	0.50±0.20
	2010	5.00±0.10	2.50±0.20	0.55±0.10	0.60±0.25	0.50±0.20
→	2512	6.35±0.10	3.20±0.20	0.55±0.10	0.60±0.25	0.50±0.20

RELIABILITY

ltem	Test Method	Acceptable criterion		
Temperature Coefficient of Resistance (T.C.R.)	$TCR(PPM/^{\circ}C) = \frac{(R_2 - R_1)}{R_1 \times (T_2 - T_1)} \times 10^6$ $R_1 = \text{Value in room temperature}$ $R_2 = \text{Value in test temperature} - 55^{\circ}C \text{ or } + 125^{\circ}C$ $T_1 = \text{Room temperature}$ $T_2 = \text{Test temperature} - 55^{\circ}C \text{ or } + 125^{\circ}C$ $Reference: IEC 60115-1 6.2$	0402: $100mΩ≤R<1000mΩ: ±1000PPM/°C$ 0603: $10mΩ≤R≤30mΩ: ±1500PPM/°C$ $30mΩ 50mΩ 0805, 1206, 1210, 1812, 2010, 2512: 10mΩ≤R≤15mΩ: ±1500PPM/°C 15mΩ 30mΩ$		
Insulation Resistance	Using the parallel clamp method: $100\pm15V_{\text{DC}}$ voltage is applied between the electrode and the substrate within 60 seconds. Test the insulation resistance between the terminal and the back of the part. Reference: IEC 60115-1 12.1.3.5	$\geq 10^9 \Omega$		
Dielectric Withstanding voltage	Apply an alternating current between the electrode and substrate, with the effective value of the maximum overload voltage referring to the DWV characteristics and maintain the pressure for 60 ± 5 seconds. Reference: IEC 60115-1 12.2.4	Test to confirm if the presence of current or arc breakdown by ≥10uA		
Short Time Overload	Apply 2.5 times of rated current or Max. Overload Current. whichever is less for 5 seconds. Reference: IEC 60115-1 8.1.4.2	1% series: \triangle R/R=±(1.0%+0.05Ω) 5% series: \triangle R/R=±(2.0%+0.05Ω)		
Intermittent Overload	Put it in the thermostat, apply 2.5 times of rated current, 1 second ON, 25 seconds OFF, count 10000^{+400}_{-0} times, take it out and stand for 60 minutes, then measure the change rate of resistance value. Reference: IEC 60115-1 8.4.4	$_{-0}^{+400}$ times, take it out and stand for 60 minutes, rate of resistance value. \triangle R/R=±(5.0%+0.05 Ω)		
Resistance to Solvent	Immerse in isopropanol solvent at room temperature (23±5°C) for 5min, wipe 10 times with a hard toothbrush, repeat 3 times, take out and blow dry for measure. Reference: IEC 60115-1 11.3.2 method1	No obvious damage, peeling, swelling phenomenon		



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ltem	Test Method	Acceptable criterion		
Solderability	Pretreatment: dry heat 155°C, 4H, after taking out, stand at room temperature for 2 hours. Test method B1: Dip the resistance in a tin furnace at 245±5°C for 5 seconds, then take it out and observe the solder area under a microscope. Method D: 260±5°C, T=30+5/-0s. Reference: J-STD-002 & IEC 60115-1 11.1.4.3	1. Solder coverage over 95% 2. No more than 5% of the partially exposed substrate, non-wetted plating or ceramic substrate part.		
Resistance to Soldering Heat	Reflow test, time above 217 °C is 60s-150s, time above 250 \pm 5°C is 30 \pm 5s. Reference: IEC 60115-1 11.2.4.3& MIL-STD-202 Method 210	$\triangle R/R = \pm (1.0\% + 0.05\Omega)$		
Thermal Shock	High and low temperature test is carried out according to the upper and lower limits of the application temperature of the parts, the residence time of the upper and lower limits of the temperature is 30min, and the temperature conversion time is less than 30s, lasting 500 cycles. Reference: IEC 60115-1 10.1.4	\triangle R/R=±(1.0%+0.05Ω)		
Solder Joint Endurance Test	The SMD resistance was welded to the test board and bent with the standard pressure block. After standing for 60 sec. under the corresponding deformation condition, the change rate of resistance value of the part was tested. Size 0402, 0603, 0805 1206, 1210 1812, 2010, 2512 Depth 5mm 3mm 2mm Reference: IEC 60115-1 9.8.4	$\Delta R/R = \pm (1.0\% + 0.05\Omega)$		
Resistance to Dry Heat	Put it in an oven at $155\pm5^{\circ}$ C for 1000^{+48}_{-0} hrs., take it out and let it stand for more than 1hr., then measure the change rate of resistance value. Reference: IEC 60115-1 7.3	1% series: \triangle R/R=±(1.0%+0.05Ω) 5% series: \triangle R/R=±(3.0%+0.05Ω)		
Loading Life in Moisture	Place it in a constant temperature and humidity box with 40±2°C and 90~96%RH and apply the rated current (IEC 60115-1 10.4 Table 22) for 1000 hrs. Take it out and stand for 30 minutes before applying rated current for 1 minute, and then measure the change rate. Reference: IEC 60115-1 10.4	1% series: \triangle R/R=±(1.0%+0.05Ω) 5% series: \triangle R/R=±(3.0%+0.05Ω)		
Load Life	Put in an oven at 70±2°C, apply rated current, 90 min ON, 30 min OFF, 1000 hrs., take out and stand for more than 60 min, then measure the resistance change rate. Reference: IEC 60115-1 7.1	1% series: \triangle R/R=±(1.0%+0.05Ω) 5% series: \triangle R/R=±(3.0%+0.05Ω)		
Low temperature load test	-55°C, unpowered, 1 hr.: Rated current for 45 minutes, then unpowered within 15 minutes, return to room temperature, take out and stand for 24 hours, then measure the change rate of resistance value. Reference: IEC 60115-1 10.2.4	1% series: \triangle R/R=±(1.0%+0.05Ω) 5% series: \triangle R/R=±(2.0%+0.05Ω)		
Shear force test	Weld the part to the PCB. Apply the corresponding test stress from the side of the part with the test terminal for 10s. Check the appearance of the welded end of the part under the stress condition. Size 0402 0603, 0805, 1206, 1210, 1812, 2010, 2512 Test force 10N 18N Reference: IEC 60115-1 9.7	Without visible damage.		

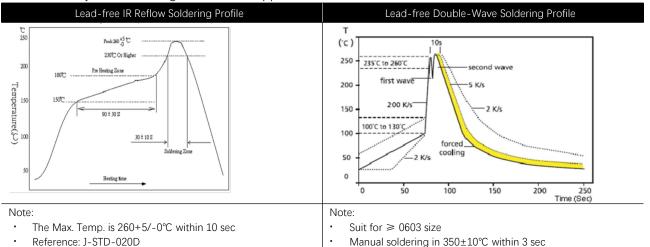
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SOLDERING

Recommendation only.

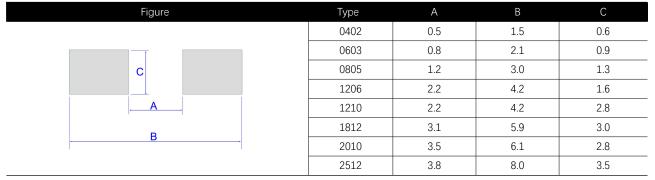
Please adjust it according to the actual application



SOLDERING PAD

Resistance value would be lower than nominal value because of joint with soldering material, so designing circuit should adjust the pad size.

Unit: mm



WORKING ENVIRONMENT

If user intends to use products in special environments or states (including but not limited to the following), it is necessary to approve special characteristics and reliability for the following or other application environments.

- A. High temperature, high moisture.
- B. Near the sea, or corrosive gas, such as Cl₂, H₂S, NH₃, SO₂ and NO₂, etc.
- C. Unverified liquids, such as water, oil, chemical or organic solvent.
- D. Unverified resin or paint to cover products.
- E. Products should be washed with water soluble cleaner even if non cleaning flux.

STORAGE / CARRY CONDITIONS

A. Temperature: 25±5°C
B. Humidity: 60±15%RH
C. Storage life: 2 years. FIFO

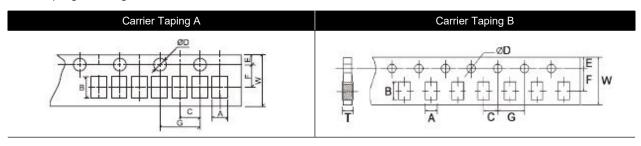
D. Please hold box correct orientation when storing and carrying. It is strictly prohibited to fall or squeeze the box, otherwise the product electrode or body may be damaged.

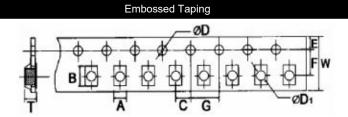
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TAPING

A. Taping drawing





B. Taping Dimensions

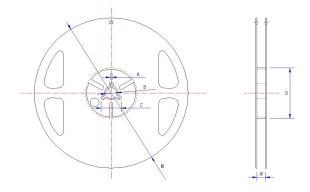
Unit: mm

Type or Size		A±0.2	B±0.2	C±0.05	$\emptyset D_{-0}^{+0.1}$	E±0.1	F±0.05	G±0.1	W±0.2	T±0.1
Carrier Taping A	0402	0.67±0.1	1.17±0.1	2.0	1.5	1.75	3.5	4.0	8.0	0.47
Carrier Taping B	0603	1.10	1.90	2.0	1.5	1.75	3.5	4.0	8.0	0.67
	0805	1.65	2.40	2.0	1.5	1.75	3.5	4.0	8.0	0.81
	1206	1.90	3.45	2.0	1.5	1.75	3.5	4.0	8.0	0.81
	1210	2.85	3.50	2.0	1.5	1.75	3.5	4.0	8.0	0.81

Type or S	iize	A±0.2	B±0.2	C±0.05	$\emptyset D_{-0}^{+0.1}$	ØD ^{+0.25}	E±0.1	F±0.05	G±0.1	W±0.2	T±0.1
Embossed Taping	2010	2.90	5.60	2.00	1.50	1.50	1.75	5.50	4.00	12.00	1.00
	1812	3.50	4.80	2.00	1.50	1.50	1.75	5.50	4.00	12.00	1.00
	2512	3.50	6.70	2.00	1.50	1.50	1.75	5.50	4.00	12.00	1.00

REEL SPECIFICATION

A. Reel drawing



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B. Reel dimension Unit: mm

Type	SPQ PCS/RI.	A±0.5	B±0.5	C±0.5	D±1	M±2	W±1
0402	10,000	2.0	13.0	21.0	60.0	178.0	10.0
0603	5,000	2.0	13.0	21.0	60.0	178.0	10.0
0805	5,000	2.0	13.0	21.0	60.0	178.0	10.0
1206	5,000	2.0	13.0	21.0	60.0	178.0	10.0
1210	5,000	2.0	13.0	21.0	60.0	178.0	10.0
1812	4,000	2.0	13.0	21.0	60.0	178.0	13.8
2010	4,000	2.0	13.0	21.0	60.0	178.0	13.8
2512	4,000	2.0	13.0	21.0	60.0	178.0	13.8

LABEL SPECIFICATION

A. Process Label (Ref.)



B. Customer Label (Ref.)

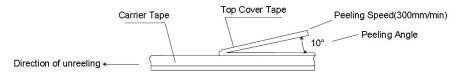


PACKING BOX

- A. Packing Type: Taping in reel / Bulk in plastic bag.
- B. Inner box: The inner box has several capacities hold 1 reel, 2 reels, 3 reels, 4 reels, 5 reels and 10 reels.
- C. Out box: The out box has two capacities hold 6- or 8-pieces inner box.

TAPING UNREEL DIRECTION

A. Figure of cover tape peel off.



- B. Please keep peeling speed under 300mm per minute.
- C. Please keep the angle between cover tape and direction of unreeling narrower than 10 degree.
- D. There is limit of adhesive force between cover tape and carrier tape or embossed tape shown as following table.

Size of chip resistors	0402	0603 and above
Adhesive force limit	10~40gf	10~70gf

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- NingBo Giantohm Micro Electronics Technology Co., Ltd. (hereinafter referred to as Giantohm, including distributors and agents, the same applies hereinafter) retains the right to interpret, update, and revise product information (specifications, data, images, etc.).
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- Damages: Any direct/indirect losses (including loss of profit, special damages, punitive damages, etc.)
 caused by improper use or application of the products, regardless of the legal theory (contract, tort, or otherwise).
- **Implied Warranties**: Exclusion of implied fitness warranties for a particular purpose, non-infringement, and merchantability (except as mandated by law).

3. Product Use Scope and Technical Advice Liability

- Statements regarding the suitability of products for certain types of applications are based on
 GiantOhm knowledge of typical requirements that are often placed on GiantOhm products in generic
 applications. Such statements are not binding statements about the suitability of products for a
 particular application. It is the user's responsibility to validate that a particular product with the
 properties described in the product specification is suitable for use in a particular application.
- Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each user application by the user's technical experts for the application, with the user assuming full responsibility.
- Except as expressly indicated in writing, GiantOhm products are not designed for use in medical, lifesaving, or life-sustaining applications or for any other application in which the failure of the GiantOhm product could result in personal injury or death. users using or selling GiantOhm products not expressly indicated for use in such applications do so at their own risk.

4. Combined Use Risk

• When the product is used in combination with other materials or processes, the Buyer assumes all risks and liabilities. GiantOhm does not warrant the suitability of the combination and shall not be liable for any responsibilities.

5. Disclaimer Updates

- The updated Terms shall prevail over previous versions and shall be subject to the latest version
 published on the official website (http://www.giantohm.com/download/cid/22.html), except for
 transactions concluded prior to the effective date of the amendments.
- Continued use of the products by the user after the Terms update shall constitute deemed acceptance
 of the new Terms.

6. Effectiveness:

• This disclaimer does not exclude liability for personal injury caused by intentional misconduct or gross negligence, or other liabilities prohibited from exclusion by law.

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VERSION HISTORY

Version	Date	Change Item(s)	Description
_A	2022/05/25		First version
В	2022/12/07	Reliability	Update test items, test method and acceptable criterion.
C	2023/03/03	Characteristics	Remarks Max. Working Voltage and Max. Overload Voltage. Add 0402 size.
D	2023/12/11	Full	Add 1812 size.
E	2024/01/23	Full	Add Packing Specifications. Add Dielectric Withstanding Voltage. Delete Max. Working Voltage and Max. Overload Voltage.
F	2024/05/29	Full	Add Moisture sensitivity level description.
G	2025/05/09	Legal Disclaimer Feature	Revise the entire text RoHS
H	2025/07/08	Label Specification	Correction of reference label template
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